

10-A, 4.75-V to 14-V INPUT, NON-ISOLATED, WIDE-OUTPUT, DIGITAL POWERTRAIN™ MODULE

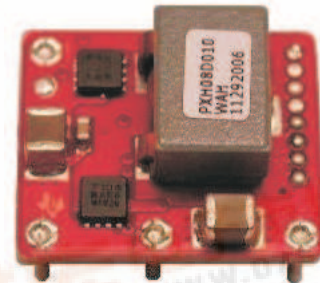
Check for Samples: [PTD08A010W](#)

FEATURES

- Up to 10-A Output Current
- 4.75-V to 14-V Input Voltage
- Programmable Wide-Output Voltage (0.7 V to 3.6 V)
- Efficiencies up to 96%
- Digital I/O
 - PWM signal
 - INHIBIT
 - Current limit flag (FAULT)
 - Synchronous Rectifier Enable (SRE)
- Analog I/O
 - Temperature
 - Output current
- Safety Agency Approvals: (Pending)
 - UL/IEC/CSA-C22.2 60950-1
- Operating Temperature: –40°C to 85°C

APPLICATIONS

- Digital Power Systems using UCD9XXX Digital Controllers



DESCRIPTION

The PTD08A010W is a high-performance 10-A rated, non-isolated digital PowerTrain module. This module is the power conversion section of a digital power system which incorporates TI's UCD7230 MOSFET driver IC. The PTD08A010W must be used in conjunction with a digital power controller such as the UCD9240 or UCD9110 family. The PTD08A010W receives control signals from the digital controller and provides parametric and status information back to the digital controller. Together, PowerTrain modules and a digital power controller form a sophisticated, robust, and easily configured power management solution.

Operating from an input voltage range of 4.75 V to 14 V, the PTD08A010W provides step-down power conversion to a wide range of output voltages from, 0.7 V to 3.6 V. The wide input voltage range makes the PTD08A010W particularly suitable for advanced computing and server applications that utilize a loosely regulated 8-V, 9.6-V or 12-V intermediate distribution bus. Additionally, the wide input voltage range increases design flexibility by supporting operation with tightly regulated 5-V or 12-V intermediate bus architectures.

The module incorporates output over-current and temperature monitoring which protects against most load faults. Output current and module temperature signals are provided for the digital controller to permit user defined over-current and over-temperature warning and fault scenarios.

The module uses double-sided surface mount construction to provide a low profile and compact footprint. Package options include both through-hole and surface mount configurations that are lead (Pb) - free and RoHS compatible.



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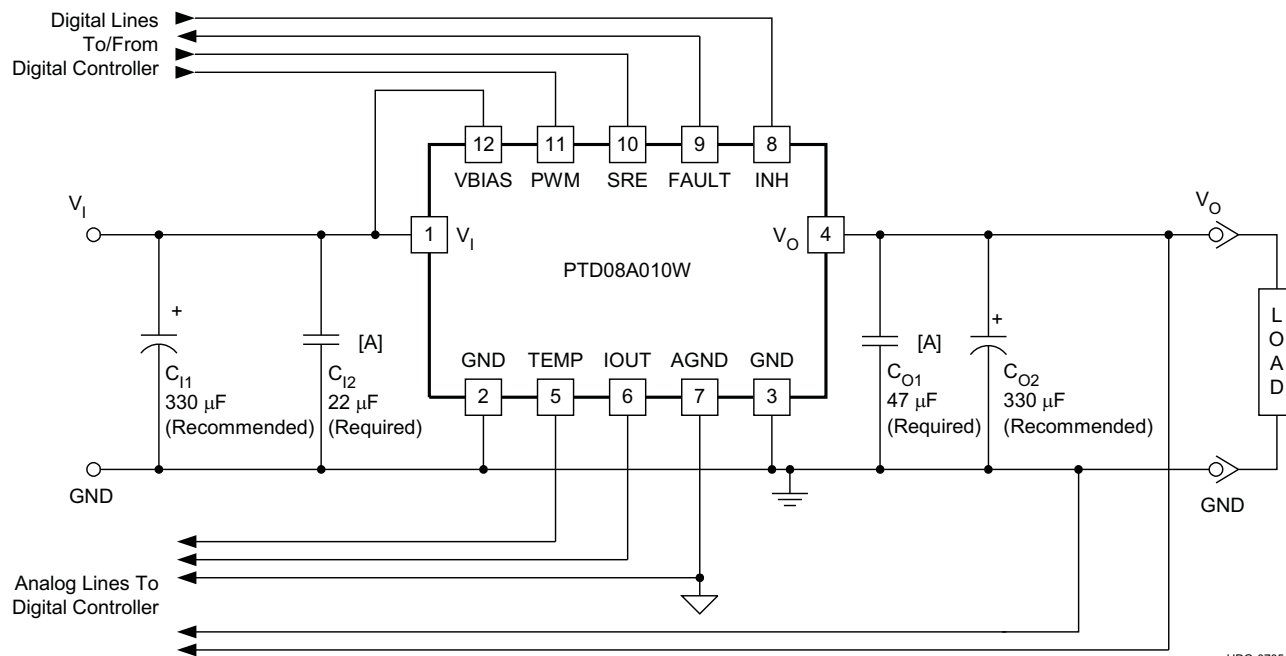


[查看 PTD08A010W 数据手册](#)


This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

Standard PTD08A010W Application



A. C_{I2} and C_{O1} are optional when the operating frequency is greater than 500 kHz.

ORDERING INFORMATION

For the most current package and ordering information, see the Package Option Addendum at the end of this datasheet, or see the TI website at www.ti.com.

DATASHEET TABLE OF CONTENTS

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ENVIRONMENTAL AND ABSOLUTE MAXIMUM RATINGS

(Voltages are with respect to GND)

| | | | | UNIT |
|-------------------|-----------------------------|--|---------------------------|--------------------|
| V_I | Input voltage | | 16 | V |
| V_B | Bias voltage | | 16 | V |
| T_A | Operating temperature range | Over V_I range | –40 to 85 | |
| T_{wave} | Wave soldering temperature | Surface temperature of module body or pins for 5 seconds maximum | 260 | °C |
| T_{stg} | Storage temperature | | –55 to 125 ⁽¹⁾ | |
| | Mechanical shock | Per Mil-STD-883D, Method 2002.3, 1 msec, 1/2 sine, mounted | 200 | G |
| | Mechanical vibration | Mil-STD-883D, Method 2007.2, 20-2000 Hz | 15 | |
| | Weight | | 3.9 | grams |
| MTBF | Reliability | Per Telcordia SR-332, 50% stress, $T_A = 40^\circ\text{C}$, ground benign | 9.4 | 10 ⁶ Hr |
| | Flammability | Meets UL94V-O | | |

(1) The shipping tray or tape and reel cannot be used to bake parts at temperatures higher than 65°C.

ELECTRICAL CHARACTERISTICS**PTD08A010W**

$T_A = 25^\circ\text{C}$, $F_{\text{SW}} = 350\text{kHz}$, $V_I = 12\text{ V}$, $V_O = 3.3\text{ V}$, $V_B = V_I$, $C_{I1} = 330\text{ }\mu\text{F}$, $C_{I2} = 22\text{ }\mu\text{F}$ ceramic, $C_{O1} = 47\text{ }\mu\text{F}$ ceramic, $C_{O2} = 330\text{ }\mu\text{F}$, and $I_O = I_{O(\text{max})}$ (unless otherwise stated)

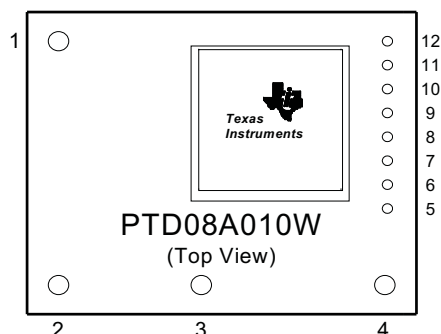
| PARAMETER | | TEST CONDITIONS | | PTD08A010W | | | UNIT |
|------------------------|------------------------------------|---|---|--------------------|--------------------|---------------------|----------------------|
| | | | | MIN | TYP | MAX | |
| I_O | Output current | Over V_O range | 25°C , natural convection | 0 | | 10 | A |
| V_I | Input voltage range | Over I_O range | | 4.75 | | 14 ⁽¹⁾ | V |
| V_{OAdj} | Output voltage adjust range | Over I_O range | | 0.7 ⁽¹⁾ | | 3.6 | V |
| η | Efficiency | $V_I = V_B = 5\text{ V}$ $I_O = 10\text{ A}$, $f_s = 350\text{ kHz}$ | $V_O = 3.3\text{ V}$ | | 95% | | |
| | | | $V_O = 2.5\text{ V}$ | | 92% | | |
| | | | $V_O = 1.8\text{ V}$ | | 89% | | |
| | | | $V_O = 1.5\text{ V}$ | | 88% | | |
| | | | $V_O = 1.2\text{ V}$ | | 86% | | |
| | | | $V_O = 1.0\text{ V}$ | | 84% | | |
| V_{OPP} | V_O Ripple (peak-to-peak) | 20-MHz bandwidth | | | 20 | | mV _{PP} |
| V_B | Bias voltage | | | 4.75 | | 14 | V |
| V_B UVLO | Bias voltage under voltage lockout | V_B increasing | | 4.25 | 4.5 | 4.75 | V |
| | | V_B decreasing | | 4.0 | 4.25 | 4.5 | |
| I_B | Bias current | Inhibit (pin 8) to AGND | Standby | | 4 | | mA |
| | | | Switching | | 34 | | |
| V_{IH} | High-level input voltage | SRE, INH, & PWM input levels | | 2.0 | | 5.5 | V |
| V_{IL} | Low-level input voltage | | | | | 0.8 | |
| | PWM input | Frequency range | | 300 | | 1000 | kHz |
| | | Pulse width limits | | 130 | | | ns |
| | TEMP output | Range | | -40 | | 125 | $^\circ\text{C}$ |
| | | Accuracy, $-40^\circ\text{C} \leq T_A \leq 85^\circ\text{C}$ | | -4 | | 6 | $^\circ\text{C}$ |
| | | Slope | | | 10 | | mV/ $^\circ\text{C}$ |
| | | Offset, $T_A = 0^\circ\text{C}$ | | | 500 | | mV |
| V_{OH} | FAULT output | High-level output voltage, $I_{\text{FAULT}} = 4\text{ mA}$ | | 2.7 | 3.3 | | V |
| V_{OL} | | Low-level output voltage, $I_{\text{FAULT}} = 4\text{ mA}$ | | | 0 | 0.6 | |
| I_{LIM} | | Overcurrent threshold; Reset, followed by auto-recovery | | | 20 | | A |
| | IOUT output | Range | | 0.15 | | 3.5 | V |
| | | Gain | | 70 | 100 | 130 | mV/A |
| | | Offset, $I_O = 0\text{ A}$, $V_O = 1.2\text{ V}$ | | 0.44 | 0.6 | 0.76 | V |
| | | Output Impedance | | 10 | 15 | 21 | k Ω |
| C_I | External input capacitance | Nonceramic | | | 330 ⁽²⁾ | | μF |
| | | Ceramic | | | 22 ⁽²⁾ | | |
| C_O | External output capacitance | Capacitance Value | Nonceramic | | 330 ⁽³⁾ | 5000 ⁽⁴⁾ | μF |
| | | | Ceramic | | 47 ⁽³⁾ | ⁽³⁾ | |
| | | Equivalent series resistance (non-ceramic) | | | 1 ⁽⁵⁾ | | m Ω |

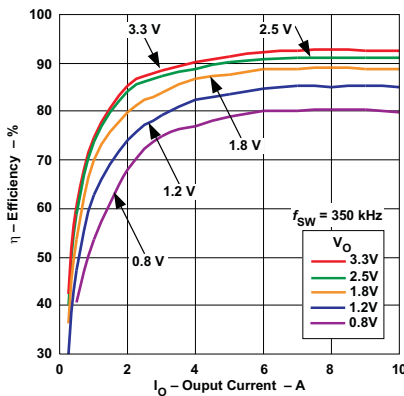
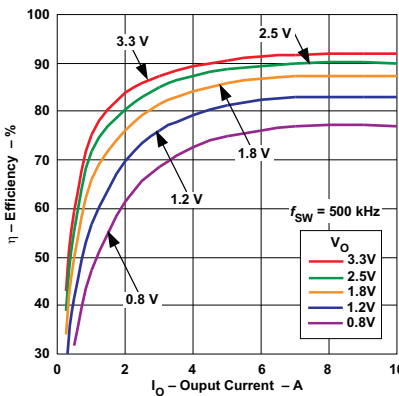
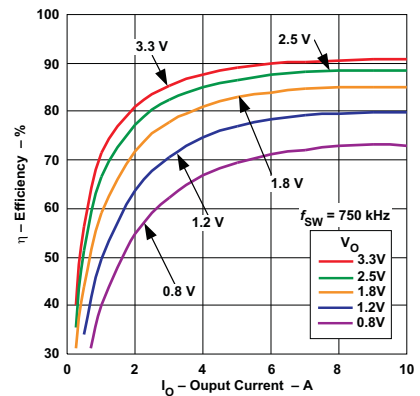
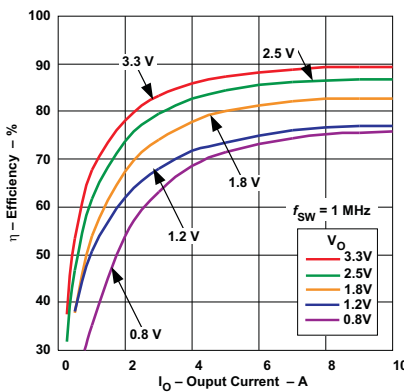
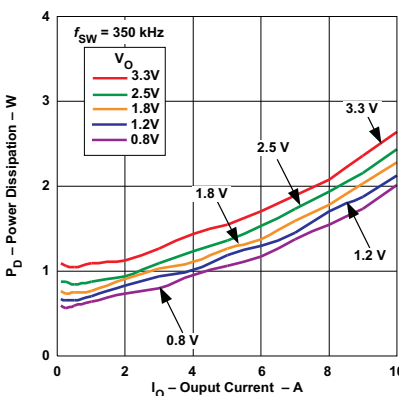
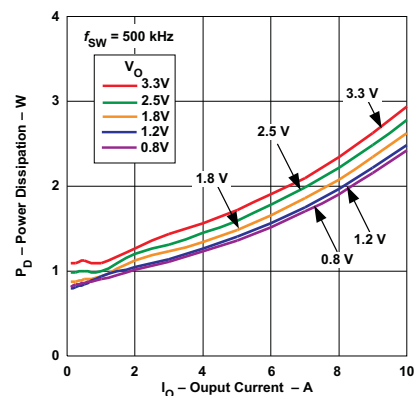
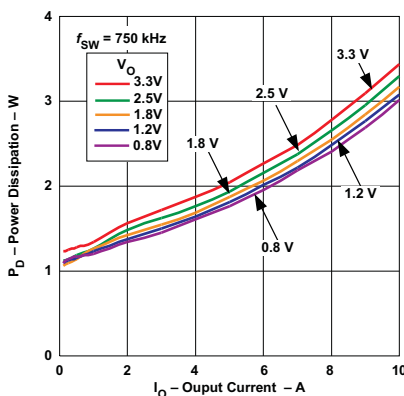
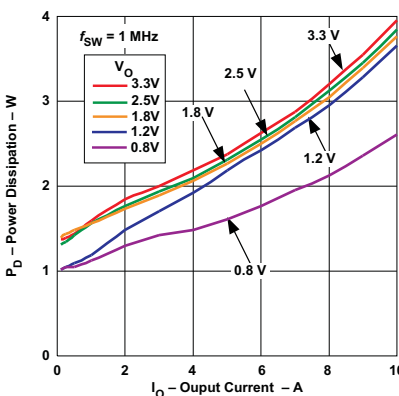
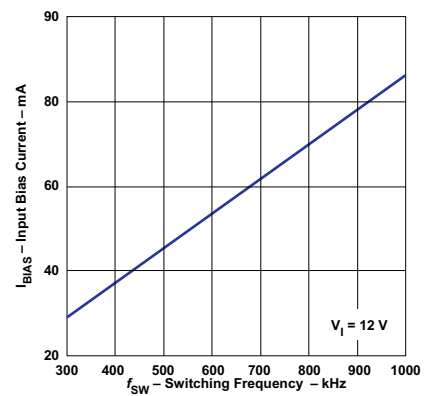
- (1) The maximum input voltage is duty cycle limited to $(V_O/(130\text{ns} \times F_{\text{SW}}))$ or 14 V, whichever is less. The maximum allowable input voltage is a function of switching frequency.
- (2) A 22 μF ceramic input capacitor is required for proper operation. An additional 330 μF bulk capacitor rated for a minimum of 500mA rms of ripple current is recommended. When operating at frequencies > 500kHz the 22 μF ceramic capacitor is only recommended. Refer to the UCD9240 controller datasheet and user interface for application specific capacitor specifications.
- (3) A 47 μF ceramic output capacitor is required for basic operation. An additional 330 μF bulk capacitor is recommended for improved transient response. When operating at frequencies > 500kHz the 47 μF ceramic capacitor is only recommended. Refer to the UCD9240 controller datasheet and user interface for application specific capacitor specifications.
- (4) 5,000 μF is the calculated maximum output capacitance given a 1V/msec output voltage rise time. Additional capacitance or increasing the output voltage rise rate may trigger the overcurrent threshold at start-up. Refer to the UCD9240 controller datasheet and user interface for application specific capacitor specifications.
- (5) This is the minimum ESR for all non-ceramic output capacitance. Refer to the UCD9240 controller datasheet and user interface for application specific capacitor specifications.

TERMINAL FUNCTIONS

| TERMINAL | | DESCRIPTION |
|--------------------|-----|--|
| NAME | NO. | |
| V_I | 1 | The positive input voltage power node to the module, which is referenced to common GND. |
| GND | 2 | This is the common ground connection for the V_I and V_O power connections. |
| | 3 | |
| V_O | 4 | The regulated positive power output with respect to GND. |
| TEMP | 5 | Temperature sense output. The voltage level on this pin represents the temperature of the module. |
| IOUT | 6 | Current sense output. The voltage level on this pin represents the average output current of the module. |
| AGND | 7 | Analog ground return. It is the 0 V_{dc} reference for the control inputs. |
| INH ⁽¹⁾ | 8 | The inhibit pin is a negative logic input that is referenced to AGND. Applying a low-level signal to this pin disables the module and turns off the output voltage. A 10 k Ω pull-up to 3.3 V or 5 V is required if the INH signal is not used. |
| FAULT | 9 | Current limit flag. The Fault signal is a 3.3 V digital output which is latched high after an over-current condition. The Fault is reset after two complete PWM cycles without an over-current condition (third rising edge of the PWM). |
| SRE | 10 | Synchronous Rectifier Enable. This pin is a high impedance digital input. A 3.3 V or 5 V logic level signals is used to enable the synchronous rectifier switch. When this signal is high, the module will source and sink output current. When this signal is low, the module will only source current. |
| PWM | 11 | This is the PWM input pin. It is a high impedance digital input that accepts 3.3 V or 5 V logic level signals up to 1 MHz. |
| VBIAS | 12 | Bias voltage supply required to power internal circuitry. For optimal performance connect VBIAS to V_I . |

(1) Denotes negative logic: High = Normal operation, Low = Function active



TYPICAL CHARACTERISTICS ($V_I = 12\text{ V}$) ⁽¹⁾**EFFICIENCY vs
LOAD CURRENT****Figure 1.****EFFICIENCY vs
LOAD CURRENT****Figure 2.****EFFICIENCY vs
LOAD CURRENT****Figure 3.****EFFICIENCY vs
LOAD CURRENT****Figure 4.****POWER DISSIPATION vs
LOAD CURRENT****Figure 5.****POWER DISSIPATION vs
LOAD CURRENT****Figure 6.****POWER DISSIPATION vs
LOAD CURRENT****Figure 7.****POWER DISSIPATION vs
LOAD CURRENT****Figure 8.****INPUT BIAS CURRENT vs
SWITCHING FREQUENCY****Figure 9.**

(1) The electrical characteristic data has been developed from actual products tested at 25°C. This data is considered typical for the converter.

TYPICAL CHARACTERISTICS ($V_I = 12\text{ V}$) Safe Operating Area ⁽¹⁾

AMBIENT TEMPERATURE vs
LOAD CURRENT

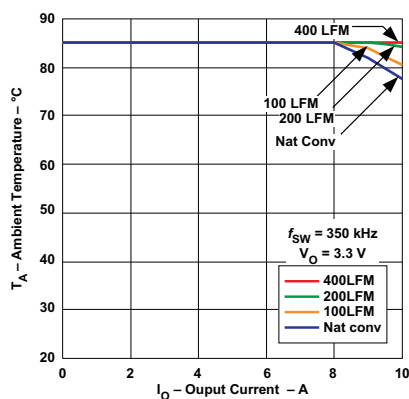


Figure 10.

AMBIENT TEMPERATURE vs
LOAD CURRENT

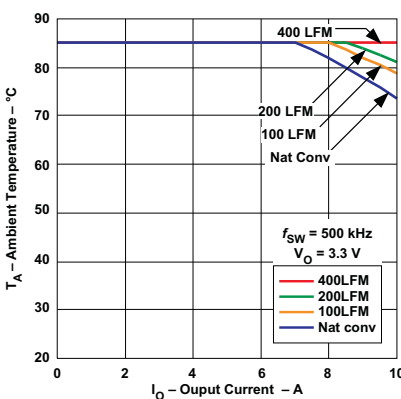


Figure 11.

AMBIENT TEMPERATURE vs
LOAD CURRENT

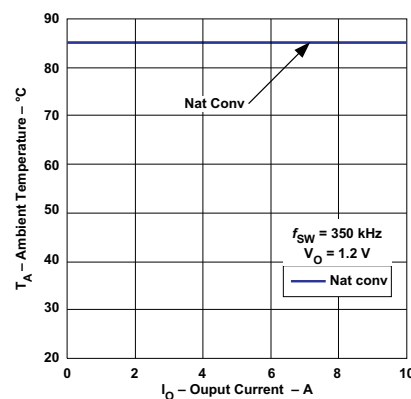


Figure 12.

AMBIENT TEMPERATURE vs
LOAD CURRENT

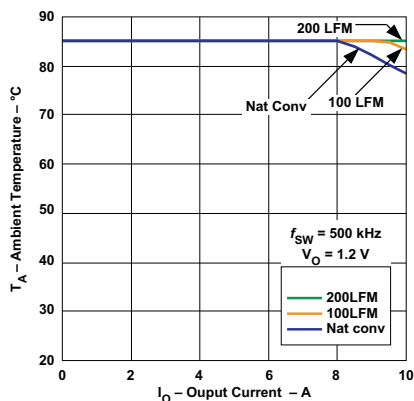


Figure 13.

AMBIENT TEMPERATURE vs
LOAD CURRENT

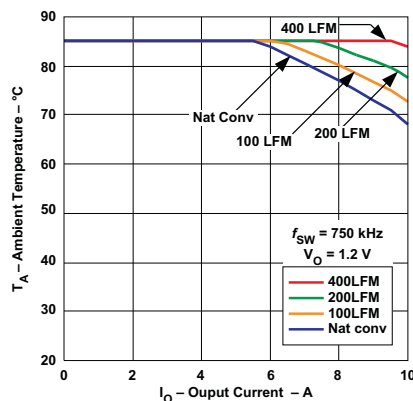
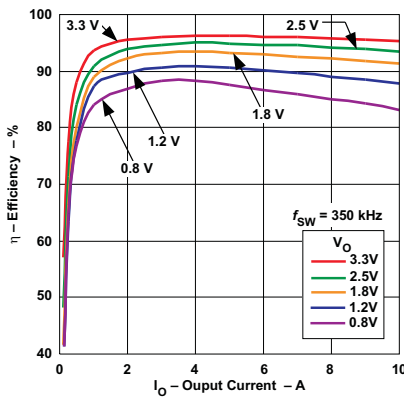
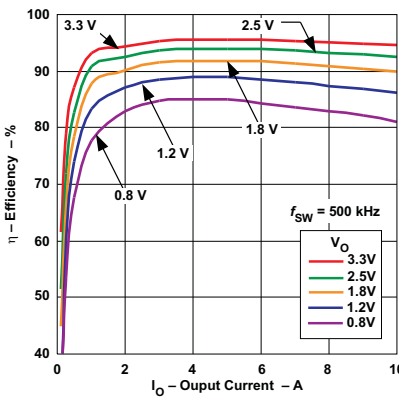
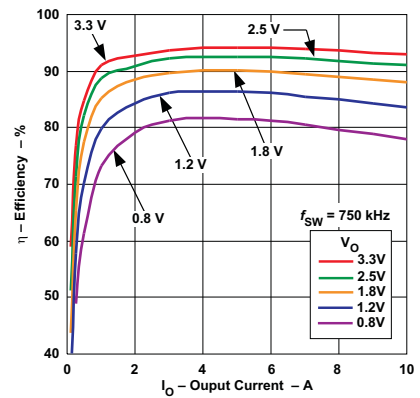
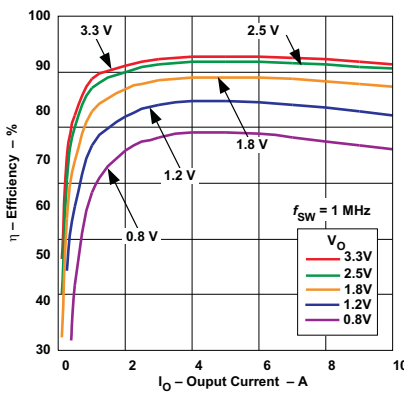
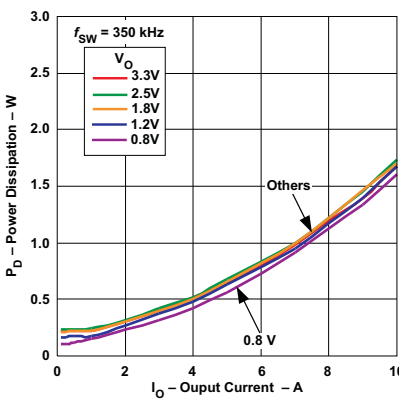
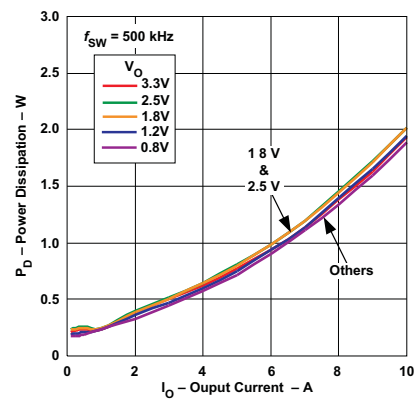
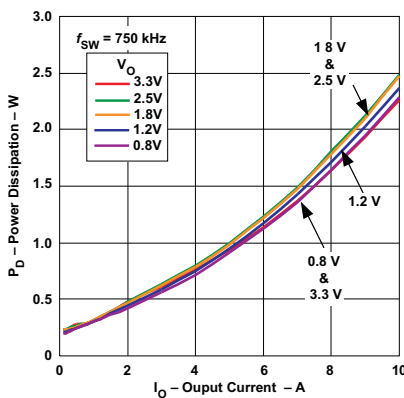
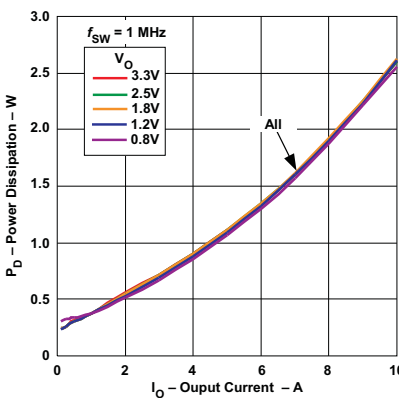
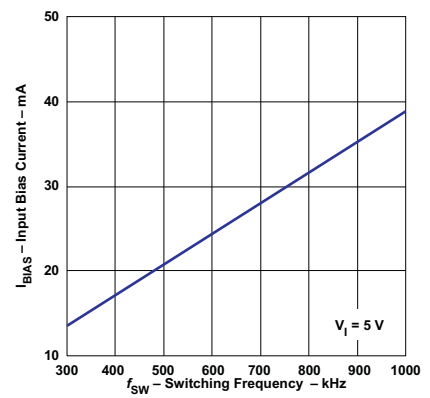


Figure 14.

- (1) The temperature derating curves represent the conditions at which internal components are at or below the manufacturer's maximum operating temperatures. Derating limits apply to modules soldered directly to a 100 mm x 100 mm double-sided PCB with 2 oz. copper. Please refer to the mechanical specification for more information.

TYPICAL CHARACTERISTICS ($V_I = 5\text{ V}$) ⁽¹⁾**EFFICIENCY vs
LOAD CURRENT****Figure 15.****EFFICIENCY vs
LOAD CURRENT****Figure 16.****EFFICIENCY vs
LOAD CURRENT****Figure 17.****EFFICIENCY vs
LOAD CURRENT****Figure 18.****POWER DISSIPATION vs
LOAD CURRENT****Figure 19.****POWER DISSIPATION vs
LOAD CURRENT****Figure 20.****POWER DISSIPATION vs
LOAD CURRENT****Figure 21.****POWER DISSIPATION vs
LOAD CURRENT****Figure 22.****INPUT BIAS CURRENT vs
SWITCHING FREQUENCY****Figure 23.**

(1) The electrical characteristic data has been developed from actual products tested at 25°C. This data is considered typical for the converter.

TYPICAL CHARACTERISTICS ($V_I = 5\text{ V}$) Safe Operating Area ⁽¹⁾

AMBIENT TEMPERATURE vs
LOAD CURRENT

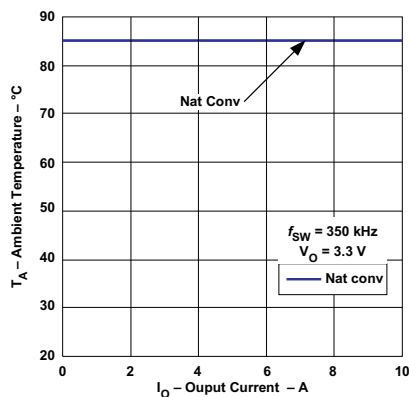


Figure 24.

AMBIENT TEMPERATURE vs
LOAD CURRENT

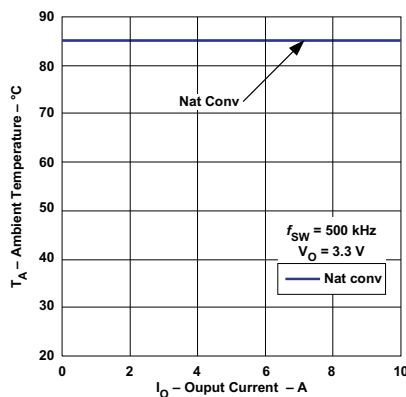


Figure 25.

AMBIENT TEMPERATURE vs
LOAD CURRENT

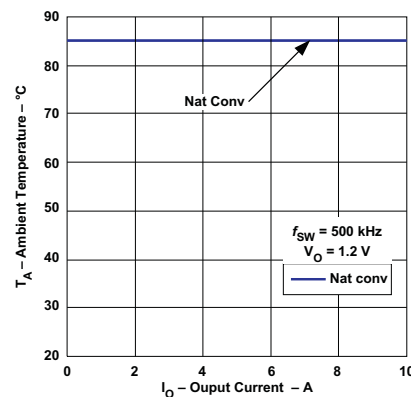


Figure 26.

AMBIENT TEMPERATURE vs
LOAD CURRENT

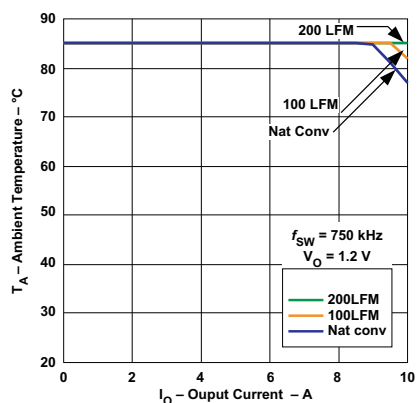


Figure 27.

- (1) The temperature derating curves represent the conditions at which internal components are at or below the manufacturer's maximum operating temperatures. Derating limits apply to modules soldered directly to a 100 mm x 100 mm double-sided PCB with 2 oz. copper. Please refer to the mechanical specification for more information.

APPLICATION INFORMATION

Digital Power

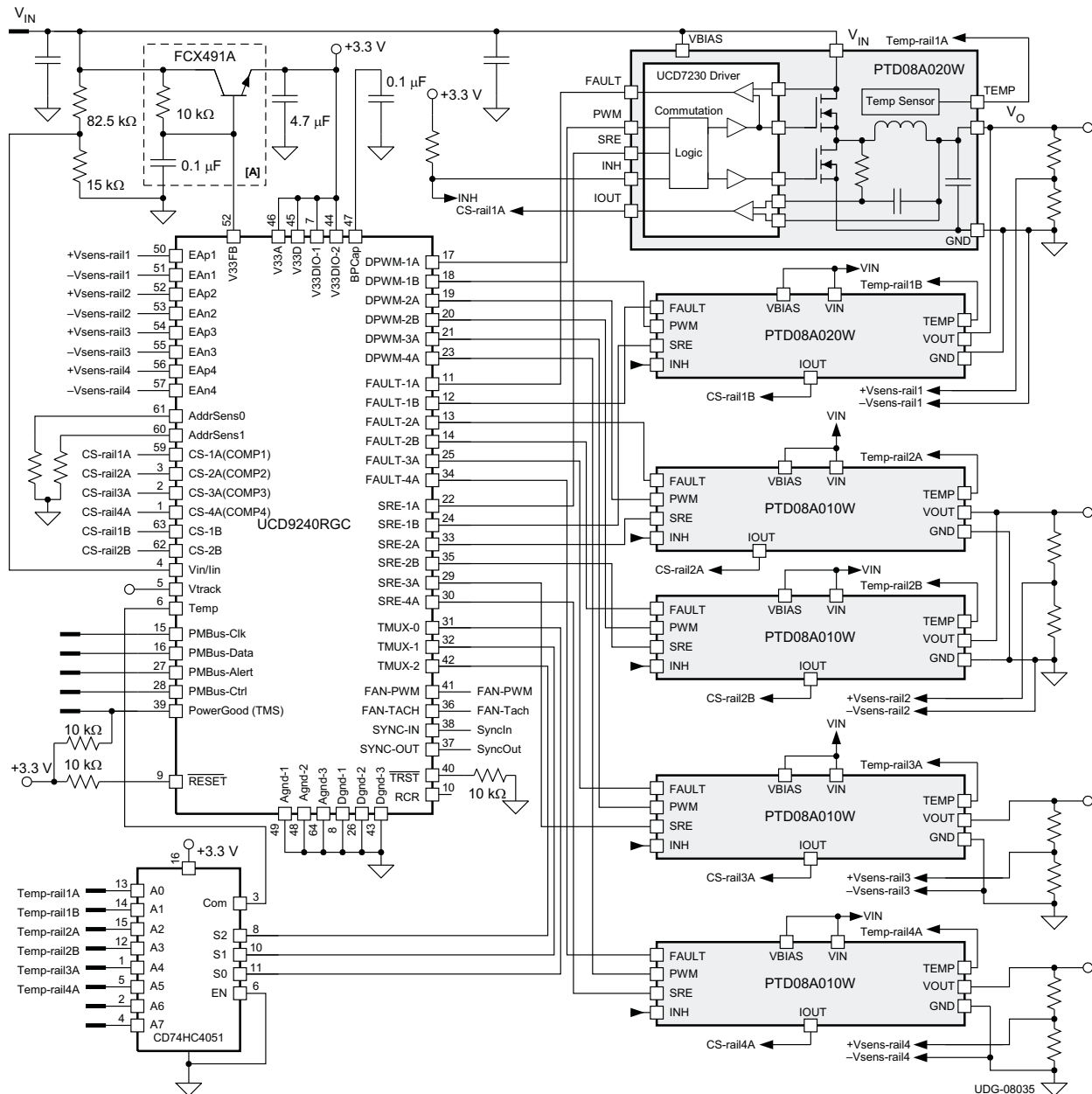


Figure 28. Typical Application Schematic

- B. This discrete bias power circuit may be substituted with a low dropout regulator (LDO). For example, [TPS715A33](#) can provide bias power to the UCD9240.

Figure 28 shows the UCD9240 power supply controller working in a system which requires the regulation of four independent power supplies. The loop for each power supply is created by the respective voltage outputs feeding into the Error ADC differential inputs, and completed by DPWM outputs feeding into the UCD7230 drivers which are shown on the PTD08A0x0W modules.

UCD9240 Graphical User Interface (GUI)

When using the UCD9240 digital controller along with digital PowerTrain modules to design a digital power system, several internal parameters of the modules are required to run the Fusion Digital Power Designer GUI. See the plant parameters below for the PTD08A010W and PTD08A020W digital PowerTrain modules.

Table 1. PTD08A010W Plant Parameters

| PTD08A010W Plant Parameters | | | |
|-----------------------------|----------|----------------|----------------|
| L (μH) | DCR (mΩ) | Rds-on-hi (mΩ) | Rds-on-lo (mΩ) |
| 0.90 | 2.2 | 3.6 | 3.6 |

Table 2. PTD08A020W Plant Parameters

| PTD08A020W Plant Parameters | | | |
|-----------------------------|----------|----------------|----------------|
| L (μH) | DCR (mΩ) | Rds-on-hi (mΩ) | Rds-on-lo (mΩ) |
| 1.0 | 1.5 | 5.0 | 2.5 |

Internal output capacitance is present on the digital PowerTrain modules themselves. When using the GUI interface this capacitance information must be included along with any additional external capacitance. See the capacitor parameters below for the PTD08A010W and PTD08A020W digital PowerTrain modules.

Table 3. PTD08A010W Capacitor Parameters

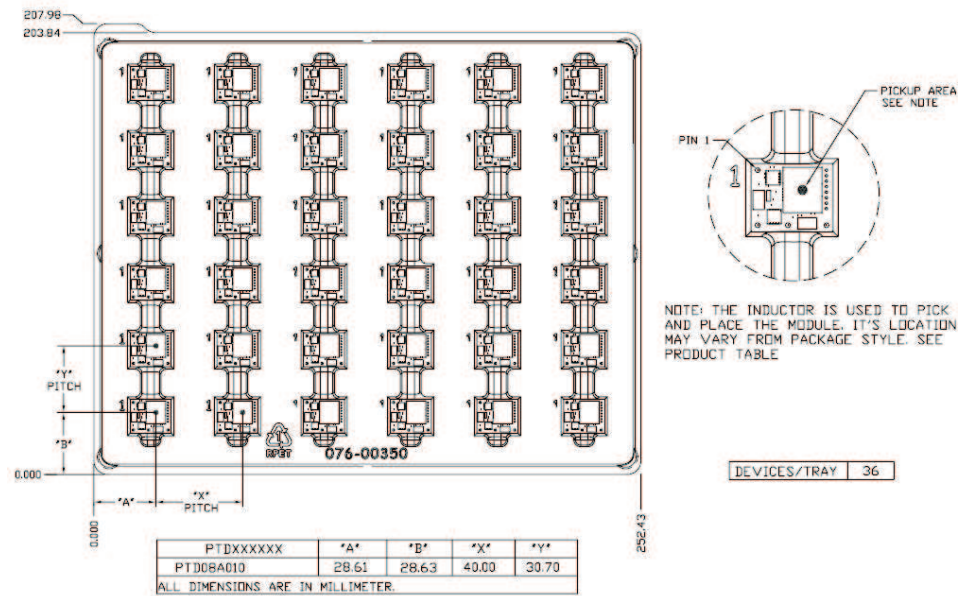
| PTD08A010W Capacitor Parameters | | | |
|---------------------------------|----------|----------|----------|
| C (μF) | ESR (mΩ) | ESL (nH) | Quantity |
| 47 | 1.5 | 2.5 | 1 |

Table 4. PTD08A020W Capacitor Parameters

| PTD08A020W Capacitor Parameters | | | |
|---------------------------------|----------|----------|----------|
| C (μF) | ESR (mΩ) | ESL (nH) | Quantity |
| 47 | 1.5 | 2.5 | 2 |

[查询 PTD08A010W 供应商](#)

TRAY





PACKAG

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/ Ball Finish | MSL Peak |
|------------------|-----------------------|---------------------|-----------------|------|-------------|-------------------------|----------------------|------------------------------|
| PTD08A010WAD | ACTIVE | Through-Hole Module | EGS | 12 | 36 | TBD | SN | Level-1-2350 Level-3-2600 |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com> for more information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all RoHS compliant products except that lead may not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in high temperature applications.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die attach between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (RoHS). This Green label adhesion denotes both RoHS and Green labels. (There may be some components that have Green labels but contain either Br or Sb based flame retardants in homogeneous material)

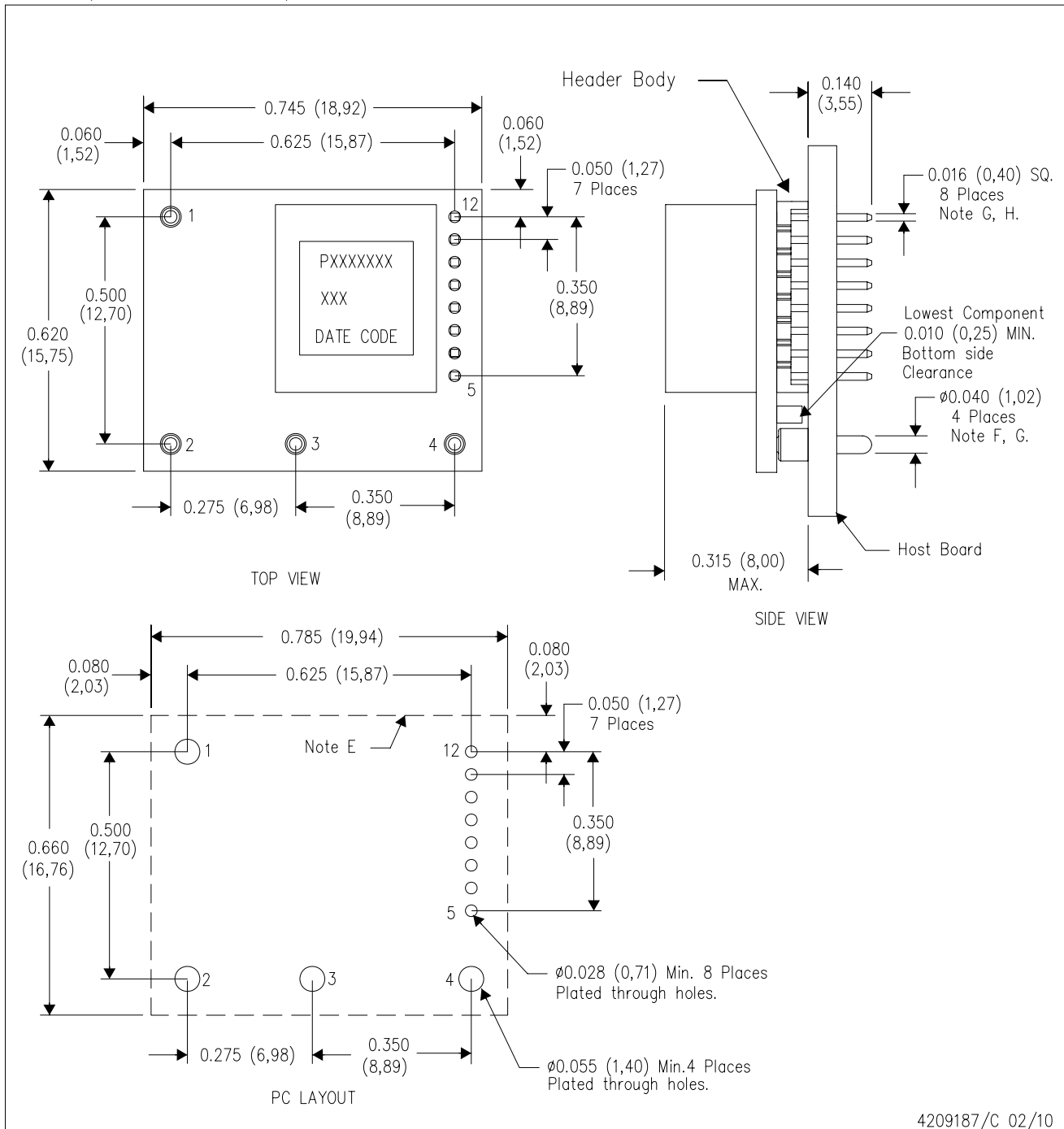
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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EGS (R-PDSS-T12)

DOUBLE SIDED MODULE



4209187/C 02/10

- NOTES:
- All linear dimensions are in inches (mm).
 - This drawing is subject to change without notice.
 - 2 place decimals are ± 0.030 ($\pm 0,76$ mm).
 - 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
 - Recommended keep out area for user components.

- Pins are 0.040" (1,02) diameter with 0.070" (1,78) diameter standoff shoulder.
- Header pins are 0.016 (0,40) SQ.
- All pins: Material – Copper Alloy
Finish – Tin (100%) over Nickel plate

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